



#### **DUAL N-CHANNEL ENHANCEMENT MODE MOSFET**

#### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub>	Ι <sub>D</sub> T <sub>A</sub> = +25°C
24V	15mΩ @ V <sub>GS</sub> = 4.5V	6.5A
	20mΩ @ V <sub>GS</sub> = 2.5V	5.6A

#### Description

This new generation MOSFET has been designed to minimize the onstate resistance ( $R_{DS(on)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

### Applications

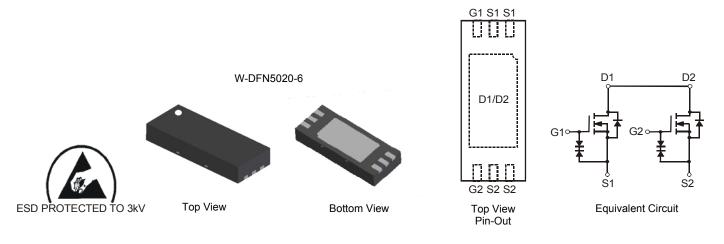
- DC-DC Converters
- Power management functions

#### Features

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected up to 3kV
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

### **Mechanical Data**

- Case: W-DFN5020-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Weight: 0.03 grams (approximate)



## Ordering Information (Note 4)

Part Number	Case	Packaging
DMG5802LFX-7	W-DFN5020-6	3000 / Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

 See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**



ME = Product Type Marking Code

- YM = Date Code Marking
- Y = Year (ex: X = 2010)
- M = Month (ex: 9 = September)

#### Date Code Key

Date Code Rey												
Year	2010	20	11	2012	2013	20	014	2015	2016	20	17	2018
Code	Х		ſ	Z	A		В	С	D		E	F
Month	lan	Feb	Mar	A.m.#	Mav	lum	Jul	A.u.a.	Sam	Oct	Nov	Dec
wonth	Jan	гер	war	Apr	way	Jun	Jui	Aug	Sep	UCL	NOV	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



#### Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Character	Symbol	Value	Unit		
Drain-Source Voltage	V <sub>DSS</sub>	24	V		
Gate-Source Voltage	V <sub>GSS</sub>	±12	V		
Continuous Drain Current (Note 5) V <sub>GS</sub> = 4.5V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	6.5 5.2	А
Continuous Drain Current (Note 5) $V_{GS}$ = 2.5V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	5.6 4.5	А
Pulsed Drain Current (Note 6)	I <sub>DM</sub>	70	А		

# **Thermal Characteristics**

Characteristic	Symbol	Max	Unit
Power Dissipation (Note 5)	PD	0.98	W
Thermal Resistance, Junction to Ambient $@T_A = +25^{\circ}C$ (Note 5)	R <sub>0JA</sub>	126.5	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	24	-		V	$V_{GS} = 0V, I_D = 250 \mu A$	
Zero Gate Voltage Drain Current TJ = +25°C	I <sub>DSS</sub>	_	—	1.0	μA	$V_{DS} = 24V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>		_	±10	μA	$V_{GS} = \pm 12V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.6	0.9	1.5	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
		_	11	15		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 6.5A	
Static Drain-Source On-Resistance	D	_	12	17	mΩ	$V_{GS} = 4V, I_D = 5.6A$	
Static Drain-Source On-Resistance	R <sub>DS (ON)</sub>		13	18	mΩ	V <sub>GS</sub> = 3.1V, I <sub>D</sub> = 5.6A	
			14	20		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 5.6A	
Forward Transfer Admittance	Y <sub>fs</sub>		17	_	S	V <sub>DS</sub> = 5V, I <sub>D</sub> = 6.5A	
Diode Forward Voltage	V <sub>SD</sub>		0.6	0.9	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1A	
DYNAMIC CHARACTERISTICS (Note 8)						•	
Input Capacitance	Ciss	_	1066.4	_			
Output Capacitance	Coss	_	132.0	_	pF	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1 0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>		127.1				
Gate Resistance	Rg	_	1.47	_	Ω	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz	
Total Gate Charge V <sub>GS</sub> = 4.5V	Qq		14.5			V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 15V, I <sub>D</sub> = 5.8A	
Total Gate Charge V <sub>GS</sub> = 10V	Qq		31.3		-0		
Gate-Source Charge	Qqs		2.0		nC	$V_{GS} = 10V, V_{DS} = 15V,$	
Gate-Drain Charge	Q <sub>qd</sub>		3.1			I <sub>D</sub> = 5.8A	
Turn-On Delay Time	t <sub>D(on)</sub>		3.69		ns		
Turn-On Rise Time	t <sub>r</sub>	_	13.43	_	ns	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15V,	
Turn-Off Delay Time	t <sub>D(off)</sub>		32.18	_	ns	$R_L = 2.1\Omega, R_G = 3\Omega$	
Turn-Off Fall Time	tf	_	22.45	_	ns	1	

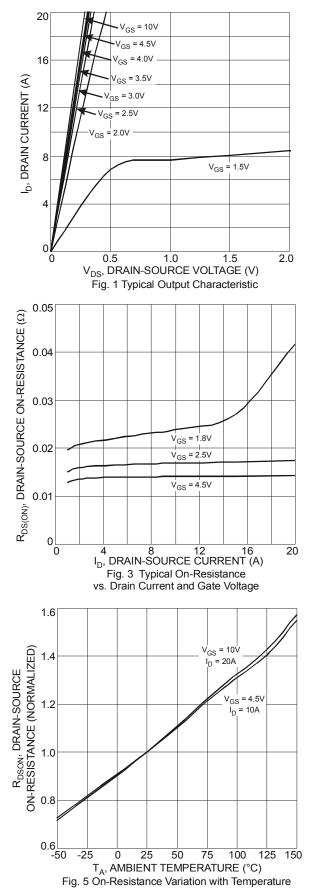
 Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
Repetitive rating, pulse width limited by junction temperature. Notes:

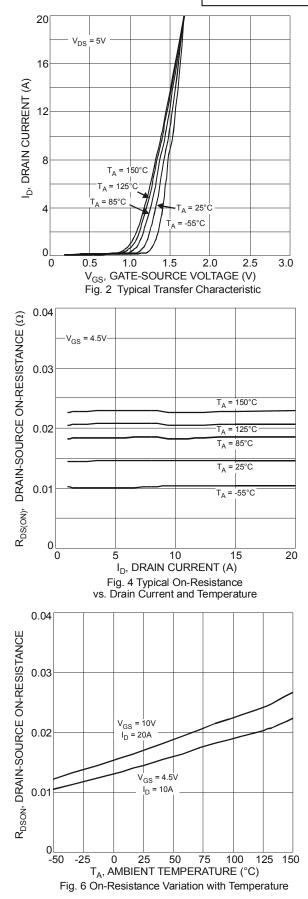
7. Short duration pulse test used to minimize self-heating effect.

8. Guaranteed by design. Not subject to production testing.



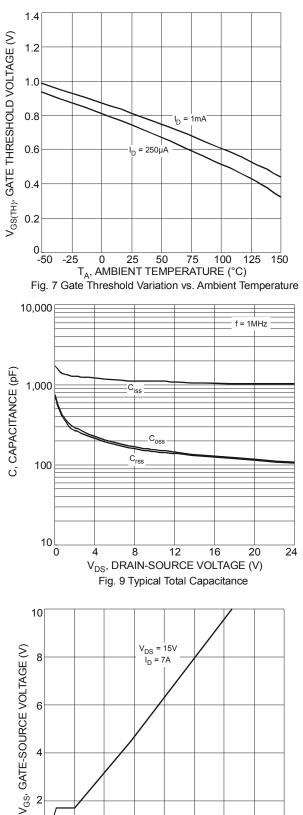
# DMG5802LFX





DMG5802LFX Document number: DS35009 Rev. 5 - 2

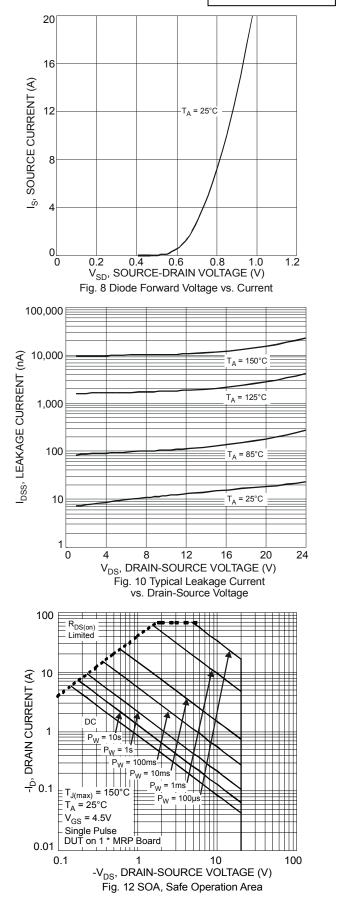




10 15 20 25 30 Q<sub>g</sub>, TOTAL GATE CHARGE (nC)

Fig. 11 Gate-Charge Characteristics

35 40



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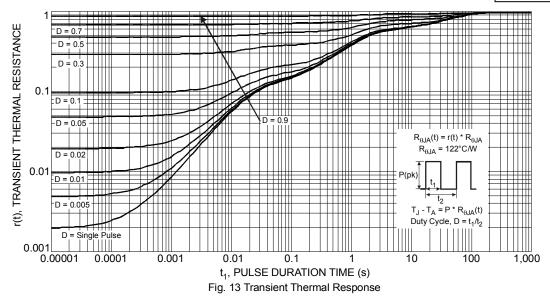
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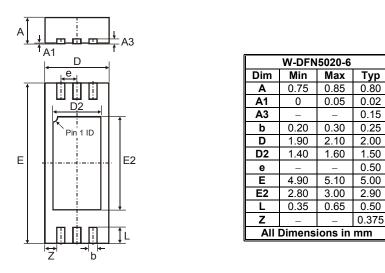
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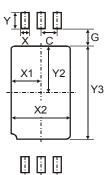
# **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



#### **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.50
G	0.35
Х	0.35
X1	0.90
X2	1.80
Y	0.70
Y2	1.60
Y3	3.20



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